

Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Value | Unit |
|------------------------------|------------------|-------|------|
| Collector-Base Voltage | V _{CBO} | -300 | V |
| Collector-Emitter Voltage | V _{CEO} | -300 | V |
| Emitter-Base Voltage | V _{EBO} | -7 | V |
| Continuous Collector Current | lc | -0.5 | Α |
| Peak Pulse Collector Current | I _{CM} | -0.75 | A |

Thermal Characteristics (@ $T_A = +25^{\circ}C$, unless otherwise specified.)

| Characteristic | Symbol | Value | Unit | |
|--|-----------------------------------|-------------|---------|--|
| Power Dissipation @T _C = +25°C | | 15 | W | |
| Power Dissipation @T _A = +25°C (Note 5) | PD | 1.56 | T vv | |
| Thermal Resistance, Junction to Case | R _{θJC} | 8.33 | °C // / | |
| Thermal Resistance, Junction to Ambient Air | R _{θJA} | 81 | °C/W | |
| Operating and Storage Temperature Range | T _J , T _{STG} | -55 to +150 | °C | |

ESD Ratings (Note 6)

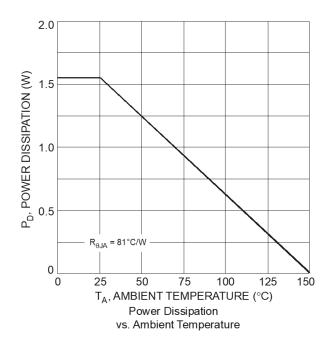
| Characteristic | Symbol | Value | Unit | JEDEC Class |
|--|---------|-------|------|-------------|
| Electrostatic Discharge - Human Body Model | ESD HBM | 4,000 | V | 3A |
| Electrostatic Discharge - Machine Model | ESD MM | 400 | V | С |

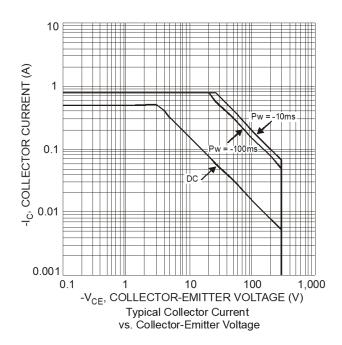
Notes:

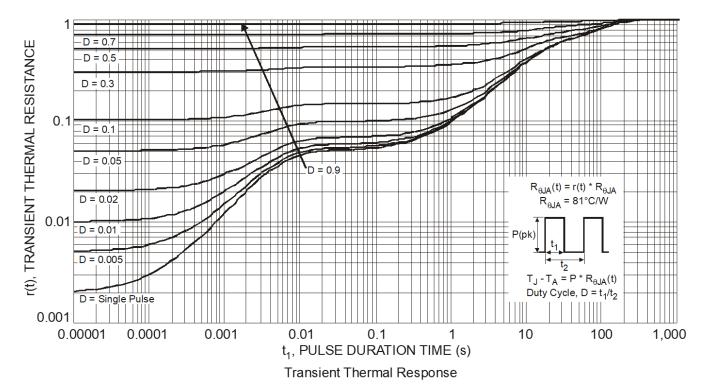
For a device mounted on FR-4 PCB with minimum recommended pad layout.
Refer to JEDEC specification JESD22-A114 and JESD22-A115.



Thermal Characteristics and Derating Information









Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

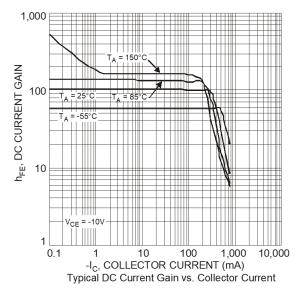
| Characteristic | Symbol | Min | Тур | Max | Unit | Test Condition |
|---|----------------------|------|-----|------|------|---|
| Collector-Emitter Breakdown Voltage (Note 7) | BV _{CEO} | -300 | _ | _ | V | $I_C = -1 \text{mA}, I_B = 0$ |
| Emitter-Base Breakdown Voltage | BV_{EBO} | -7 | _ | _ | V | $I_C = -100\mu A, I_E = 0$ |
| Collector Cut-off Current | I _{CBO} | _ | _ | -100 | nA | $V_{CB} = -300V, I_{E} = 0$ |
| Emitter Cut-off Current | I _{EBO} | _ | _ | -100 | nA | $V_{EB} = -5.6V, I_{C} = 0$ |
| Collector-Emitter Saturation Voltage (Note 7) | V _{CE(SAT)} | _ | _ | -0.5 | V | $I_C = -100 \text{mA}, I_B = -10 \text{mA}$ |
| Base-Emitter Saturation Voltage (Note 7) | V _{BE(SAT)} | _ | _ | -1.0 | V | $I_C = -100 \text{mA}, I_B = -10 \text{mA}$ |
| Base-Emitter Turn-On Voltage (Note 7) | V _{BE(ON)} | _ | _ | -1.0 | V | I _C = -100mA, V _{CE} = -5V |
| DC Current Gain (Note 7) | h _{FE} | 30 | _ | 240 | _ | $V_{CE} = -10V, I_{C} = -50mA$ |
| Current Gain-Bandwidth Product | f⊤ | 10 | _ | _ | MHz | $I_C = -50 \text{mA}, V_{CE} = -10 \text{V}, f = 10 \text{MHz}$ |

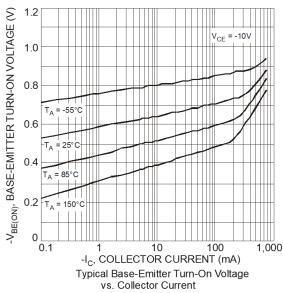
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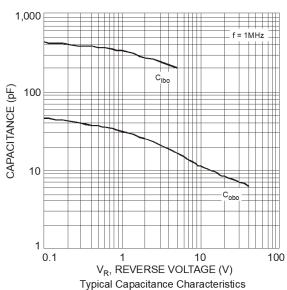
Note: 7. Measured under pulsed conditions. Pulse width \leq 300 μ s. Duty cycle \leq 2%.

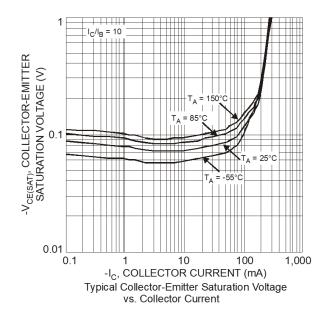


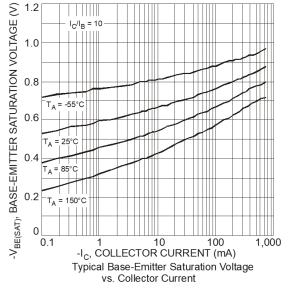
Typical Electrical Characteristics (@TA = +25°C, unless otherwise specified.)









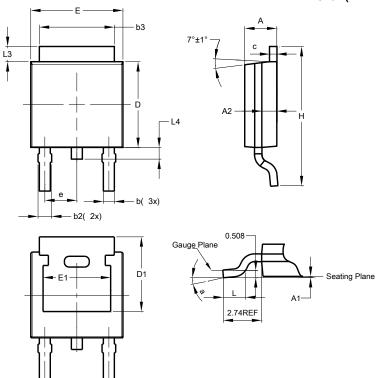




Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

TO252 (DPAK)

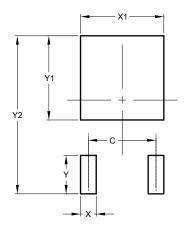


| TO252 (DPAK) | | | | | |
|----------------------|------|-------|-------|--|--|
| | | | , | | |
| Dim | Min | Max | Тур | | |
| Α | 2.19 | 2.39 | 2.29 | | |
| A 1 | 0.00 | 0.13 | 0.08 | | |
| A2 | 0.97 | 1.17 | 1.07 | | |
| b | 0.64 | 0.88 | 0.783 | | |
| b2 | 0.76 | 1.14 | 0.95 | | |
| b3 | 5.21 | 5.46 | 5.33 | | |
| С | 0.45 | 0.58 | 0.531 | | |
| D | 6.00 | 6.20 | 6.10 | | |
| D1 | 5.21 | - | - | | |
| е | - | - | 2.286 | | |
| Е | 6.45 | 6.70 | 6.58 | | |
| E1 | 4.32 | - | - | | |
| Н | 9.40 | 10.41 | 9.91 | | |
| L | 1.40 | 1.78 | 1.59 | | |
| L3 | 0.88 | 1.27 | 1.08 | | |
| L4 | 0.64 | 1.02 | 0.83 | | |
| а | 0° | 10° | | | |
| All Dimensions in mm | | | | | |

Suggested Pad Layout

 $\label{prop:lease} Please see \ http://www.diodes.com/package-outlines.html \ for \ the \ latest \ version.$

TO252 (DPAK)



| Dimensions | Value (in mm) |
|------------|---------------|
| С | 4.572 |
| Х | 1.060 |
| X1 | 5.632 |
| Υ | 2.600 |
| Y1 | 5.700 |
| Y2 | 10 700 |

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.



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